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(54) Title: METHODS OF FORMING FULLY EMBEDDED BUMPLESS BUILD-UP LAYER PACKAGES AND STRUCTURES FORMED THEREBY

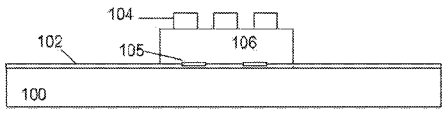


FIG.1a

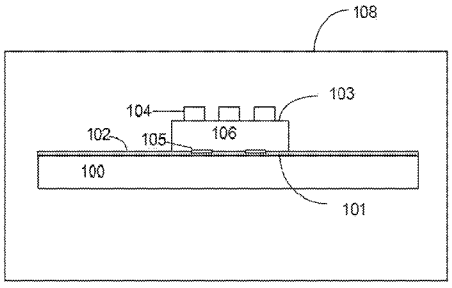


FIG.1b

(57) Abstract: Methods of forming a microelectronic packaging structure and associated structures formed thereby are described. Those methods may include a die embedded in a coreless substrate, wherein a mold compound surrounds the die, and wherein the die comprises TSV connections on a first side and C4 pads on a second side of the die, a dielectric material on a first side and on a second side of the mold compound; and interconnect structures coupled to the C4 pads and to the TSV pads. Embodiments further include forming packaging structures wherein multiple dies are fully embedded within a BBUL package without PoP lands.

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